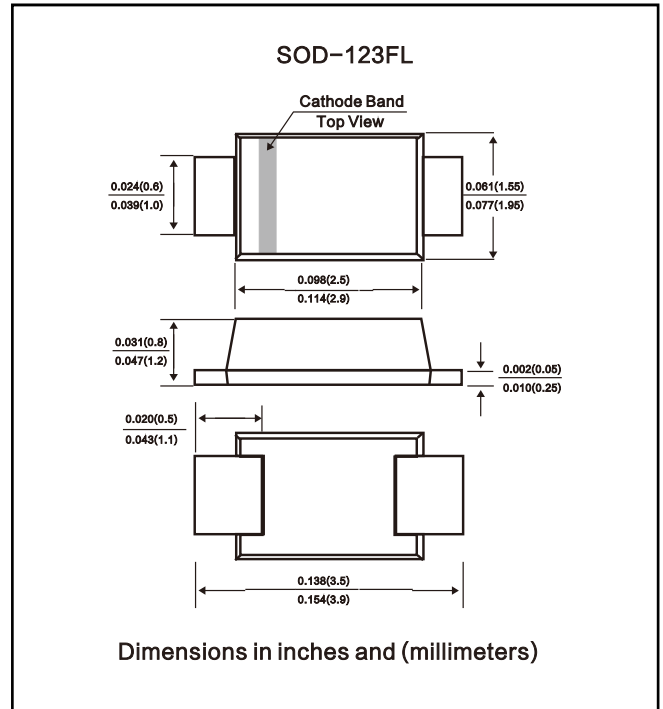


FEATURES

- Low profile package
- Ideal for automated placement
- Ultrafast reverse recovery time
- Low power losses, high efficiency
- Low forward voltage drop
- High surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

MECHANICAL DATA

- **Case:** JEDEC SOD-123FL molded plastic body over passivated chip
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- **Polarity:** Laser band denotes cathode end
- **Weight:** 0.017gram



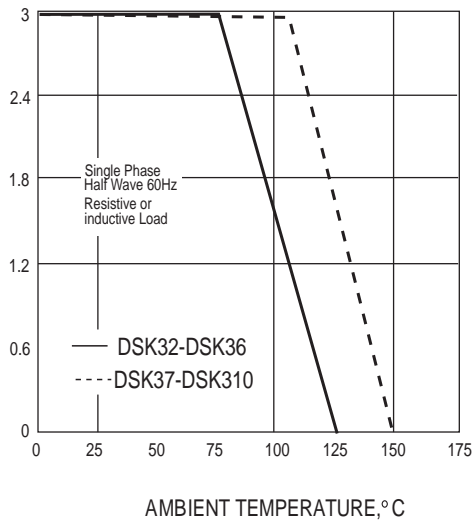
MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

MDD Catalog Number	SYMBOLS	SS 32D1F	SS 33D1F	SS 34D1F	SS 35D1F	SS 36D1F	SS 37D1F	SS 38D1F	SS 39D1F	SS 310D1F	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	70	80	90	100	VOLTS
Maximum RMS voltage	V_{RMS}	14	21	28	35	42	49	56	63	70	VOLTS
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	70	80	90	100	VOLTS
Maximum average forward rectified current	$I_{(AV)}$	3.0									Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	70.0									Amps
Maximum instantaneous forward voltage at 3.0A	V_F	0.52	0.55	0.70			0.85			Volts	
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	I_R	0.5					20.0		10.0		mA
Operating junction temperature range	T_J	-50 to +125					-50 to +150			°C	
Storage temperature range	T_{STG}	-50 to +150									°C

AVERAGE FORWARD RECTIFIED CURRENT, AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



PEAK FORWARD SURGE CURRENT, AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

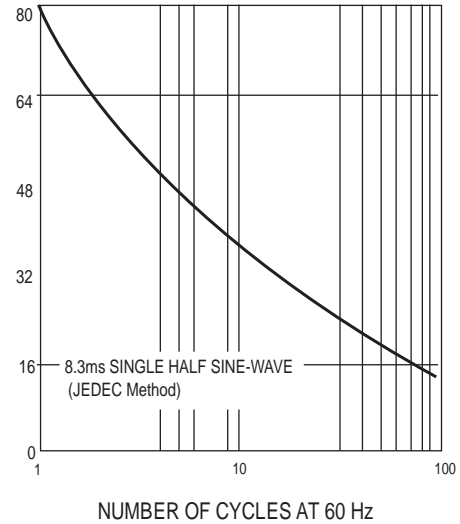


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

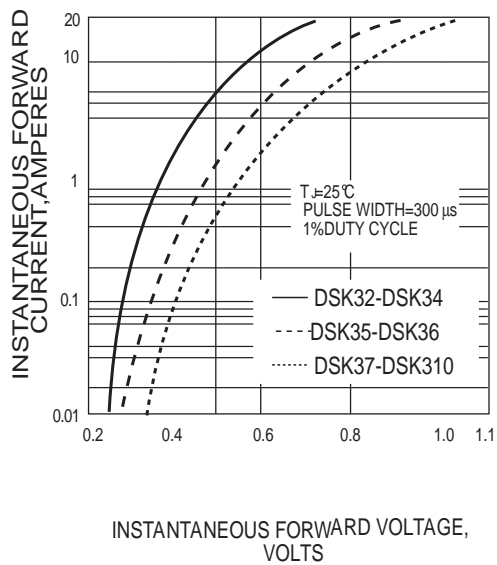


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

